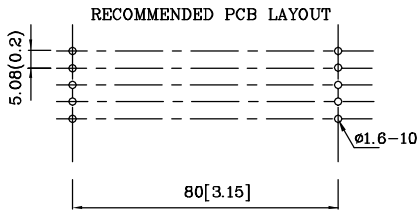
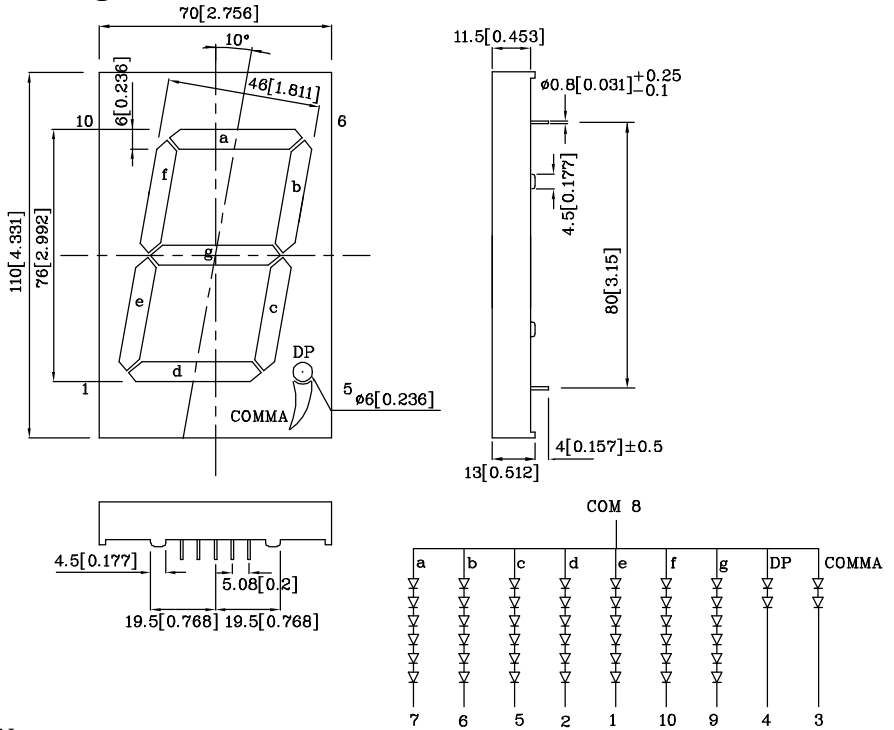


**Features**

- Low power consumption
- Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant



**Package Schematics**



**Notes:**

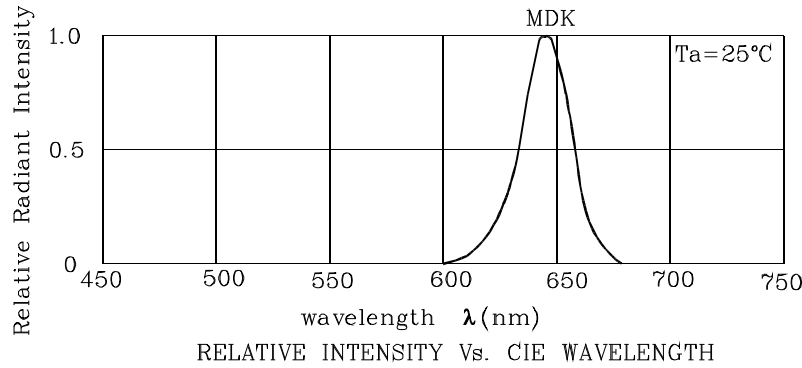
1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01") unless otherwise noted.
2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)		MDK (AlGaInP)	Unit
Reverse Voltage (Per Chip)	V <sub>R</sub>	5 (5)	V
Forward Current (Dp and Comma)	I <sub>F</sub>	30 (30)	mA
Forward Current (Peak) (Dp and Comma) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	185 (185)	mA
Power Dissipation (Dp and Comma)	P <sub>D</sub>	450 (150)	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds		

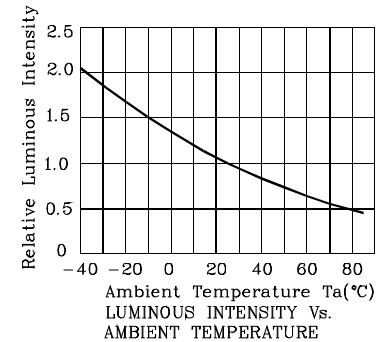
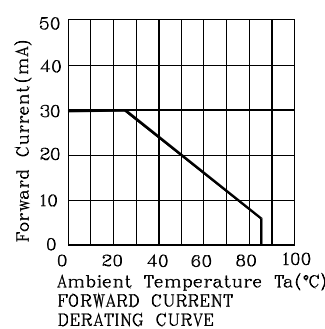
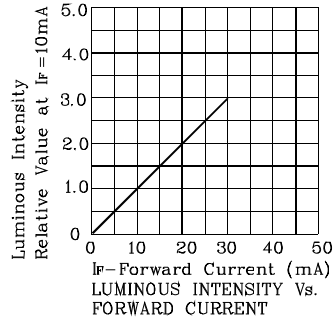
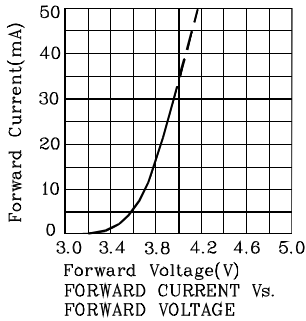
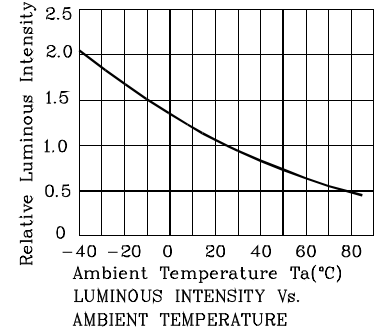
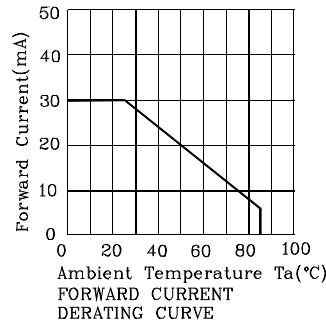
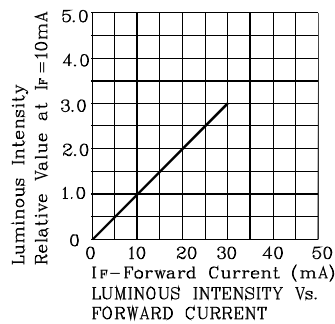
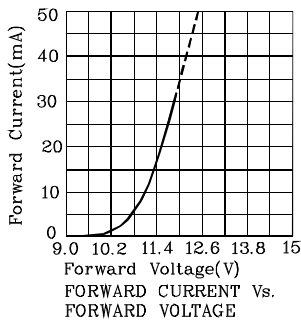
Operating Characteristics (T <sub>A</sub> =25°C)		MDK (AlGaInP)	Unit
Forward Voltage (Typ.) (Dp and Comma) (I <sub>F</sub> =10mA)	V <sub>F</sub>	11.1 (3.7)	V
Forward Voltage (Max.) (Dp and Comma) (I <sub>F</sub> =10mA)	V <sub>F</sub>	15 (5.0)	V
Reverse Current (Max.) (Per Chip) (V <sub>R</sub> =5V)	I <sub>R</sub>	10 (10)	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I <sub>F</sub> =10mA)	λ <sub>P</sub>	645*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I <sub>F</sub> =10mA)	λ <sub>D</sub>	630*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =10mA)	Δλ	28	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	C	35	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I <sub>F</sub> =10mA) ucd		Wavelength CIE127-2007* nm λ <sub>P</sub>	Description
			min.	typ.		
XDMDK76A-A	Red	AlGaInP	150000 52000*	329990 109990*	645*	Common Anode , Rt.Hand Decimal.

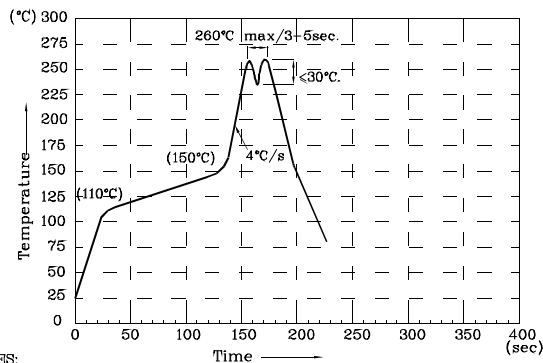
\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



❖ MDK



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- NOTES:
- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
  - 2.Do not apply stress on epoxy resins when temperature is over 85°C.
  - 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
  - 4.During wave soldering, the PCB top-surface temperature should be kept below 105°C.
  - 5.No more than once.

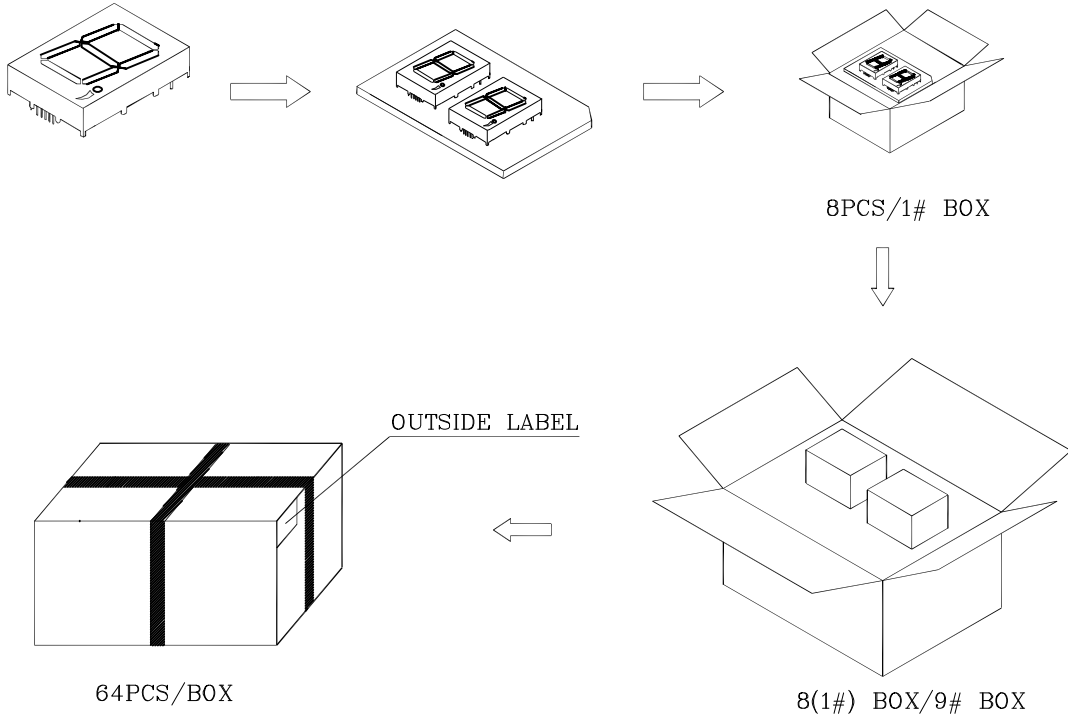
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

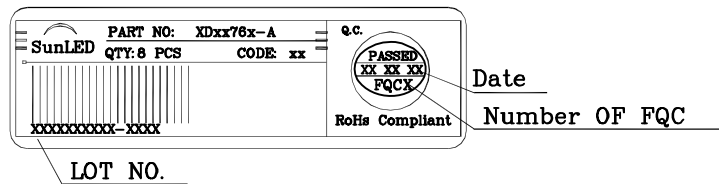
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS



Inside Label On 1#BOX



Outside Label On Box

